

A multi-objective feature selection and self-paced ensemble framework for semiconductor defect detection

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ABSTRACT

In semiconductor manufacturing, defect detection is commonly performed using high-dimensional process data. These data often exhibit class imbalance and class overlap, which create challenges for achieving reliable classification performance. To address these issues, this study proposes a multi-objective feature selection and self-paced ensemble (MOFS-SPE) framework. The framework employs a multi-objective evolutionary algorithm based on decomposition (MOEA/D) for feature selection. In this process, the area under the precision-recall curve (AUPRC) and the *R*-value are used as objective functions to identify feature subsets that are highly relevant to quality outcomes. In addition, the framework integrates the self-paced ensemble (SPE) with tree-based classifiers to handle imbalanced and overlapping data. Experiments conducted on a real semiconductor manufacturing dataset (SECOM dataset) demonstrate the effectiveness of the proposed approach. Compared with using the full feature set, the selected features increase the area under the receiver operating characteristic curve (AUROC) from 0.685 to 0.770 and the AUPRC from 0.932 to 0.972. When applying the SPE framework, the specificity of the decision tree model improves from 0.048 to 0.667, thereby enhancing the reliability of identifying defective products. Overall, the proposed framework provides a useful reference for intelligent quality inspection in semiconductor production environments.

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Večkriterijska izbira značilnik in ansambelski pristop z učenjem v lastnem tempu za zaznavanje napak v polprevodniški proizvodnji

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POVZETEK

V polprevodniški proizvodnji se zaznavanje napak običajno izvaja na podlagi visokodimenzionalnih procesnih podatkov. Ti podatki pogosto izkazujejo neuravnoteženost in prekrivanje razredov, kar predstavlja pomemben izziv za doseganje zanesljive klasifikacijske učinkovitosti. Za reševanje teh težav prispevek predlaga veškriterijski pristop za izbiro značilnik in ansambelsko učenje v lastnem tempu (MOFS-SPE). Predlagani pristop za izbiro značilnik uporablja veškriterijski evolucijski algoritem na osnovi dekompozicije (MOEA/D). V tem postopku sta kot ciljni funkciji uporabljeni površina pod krivuljo natančnost-odziv (AUPRC) in vrednost R, s katerima se identificirajo podmnožice značilnik, ki so močno povezane s kakovostnimi kazalniki. Poleg tega pristop združuje ansambelsko učenje v lastnem tempu (SPE) z drevesnimi klasifikatorji za učinkovito obravnavo neuravnoteženih in prekrivajočih se podatkov. Eksperimenti, izvedeni na realnem naboru podatkov iz polprevodniške proizvodnje (podatkovni nabor SECOM), potrjujejo učinkovitost predlaganega pristopa. V primerjavi z uporabo celotnega nabora značilnik izbrane značilke povečajo površino pod krivuljo ROC (AUROC) z 0,685 na 0,770 ter AUPRC z 0,932 na 0,972. Pri uporabi SPE se specifičnost modela odločitvenega drevesa izboljša z 0,048 na 0,667, kar bistveno poveča zanesljivost prepoznavanja okvarjenih izdelkov. Predlagani pristop predstavlja uporabno referenco za inteligentno kontrolo kakovosti v proizvodnji polprevodnikov.

PODATKI O ČLANKU

Ključne besede:

Proizvodnja polprevodnikov;
Zaznavanje napak;
Kontrola kakovosti;
Neuravnoteženost razredov;
Prekrivanje razredov;
Večkriterijska izbira značilnik;
Ansambelsko učenje v lastnem tempu;
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